



Printed Circuit Boards
Interconnection Carriers

PRINTED CIRCUIT BOARDS

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 276 FR4 70 L36.70 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_276_FR4_70_L36.70_p18

Layers	in μ	Material	Build-Up	Assembly	
Layer-1	70 μ	Copper			
	180 μ	Prepreg			
	180 μ	Prepreg			
	180 μ	Prepreg			
Layer-2	70 μ	Copper			A1
	360 μ	L-FR4			
Layer-3	70 μ	Copper			B
	180 μ	Prepreg			
	180 μ	Prepreg			
Layer-4	180 μ	Prepreg			A2
	70 μ	Copper			
	360 μ	L-FR4			
Layer-5	70 μ	Copper		B	
	180 μ	Prepreg			
	180 μ	Prepreg			
Layer-99	180 μ	Prepreg		B	
	70 μ	Copper			
	70 μ	Copper			

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